

# Welkom bij O-leading

O-Leading streeft ernaar uw one-stop oplossingspartner te zijn in EMS supply chain, inclusief PCB-ontwerp, PCB-fabricage en PCB-assemblage (PCBA). We bieden enkele van de meest geavanceerde PCB-technologie, waaronder HDI-PCB's, meerlagige PCB's, rigide flexibele PCB's . We kunnen ondersteunen van quick turn prototype tot medium & massaproductie.

Over het algemeen zijn onze wereldwijde klanten erg onder de indruk van onze diensten: snelle reactie, concurrerende prijs en kwaliteitsbewustzijn. Het bieden van meer waardevolle technische service en een algehele oplossing is de weg die O-leidend is.

Met het oog op de toekomst zal O-leading zich zoals altijd concentreren op de innovatie en ontwikkeling van elektronica-productietechnologie, en zich voortdurend inspannen voor de one-stop-service van PCB & PCBA om eersteklas services te bieden en meer waarde voor onze klanten te creëren.

Lagen: 2

Materiaal: FR4

Afgewerkte dikte: 1,57 mm +/- 10%

Buitenlaag koperdikte: 1oz

Voltooien: ENIG (Au: 2-5u ")

Soldeermasker (kleur): Beide zijden, LPI (zwart)

Zeefdruk (kleur): beide zijden, wit

Elektrische test

AFWERKING: DEZE RAAD ZAL GOUD VERGULD WORDEN VOLGENS IPC-6012.

DIKTE IS .050 uM MEER DAN 3-6 uM NIKKEL.

KOPEREN PLAAT GATEN MINIMUM .025 AVG, .020 MIN .. GATEN KUNNEN NIET WORDEN GEPLUGD, BEHALVE VIAS .500 AFWERKING OF KLEINER.

Laag sleutel:

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\* .GM4: Board Outline

\* .TXT: NC-boorbestand

\* .GTP: Top plakken

\* .GTO: Top zeefdruk

\* .GTS: Top soldeermasker

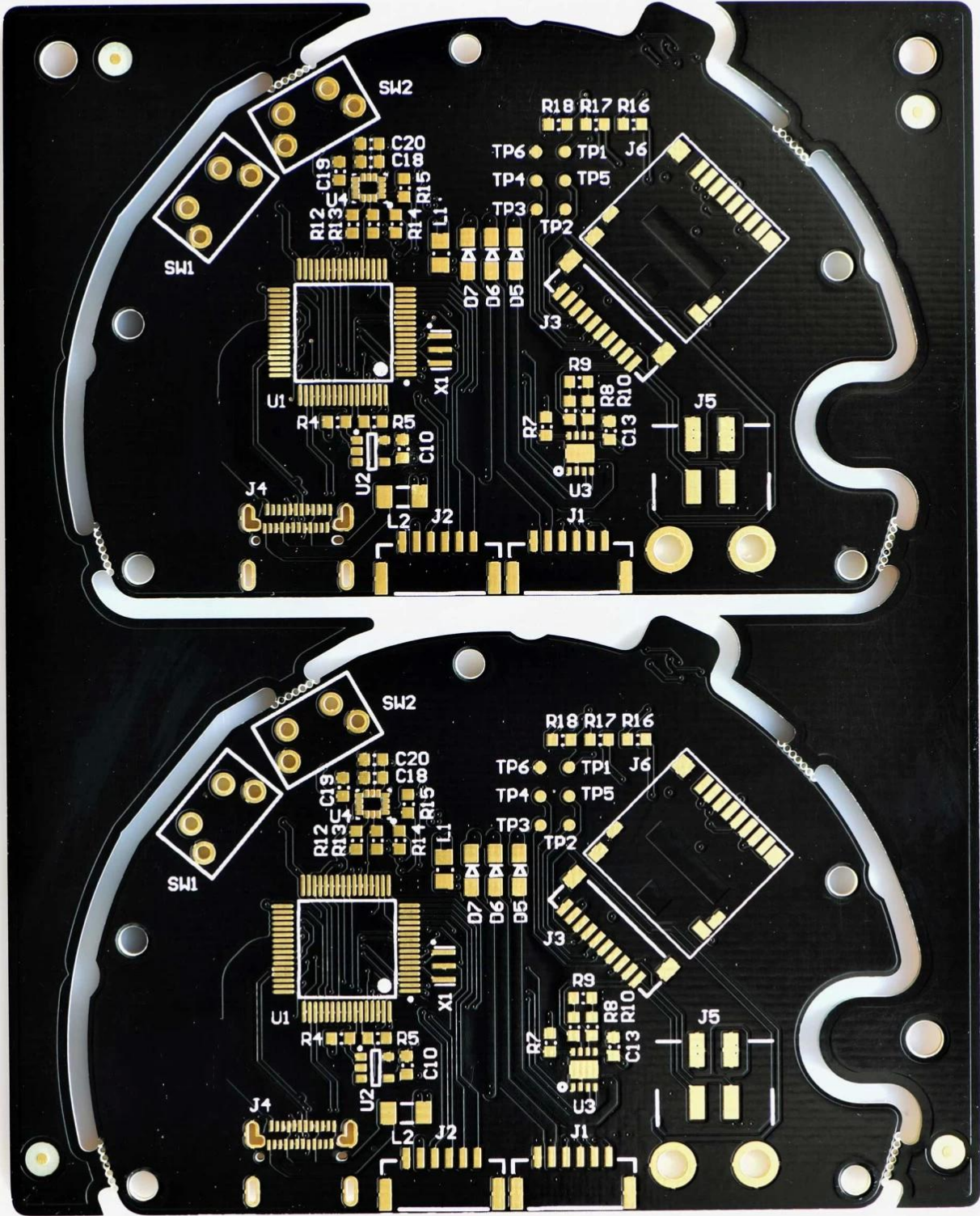
\* .GTL: bovenste koperen laag

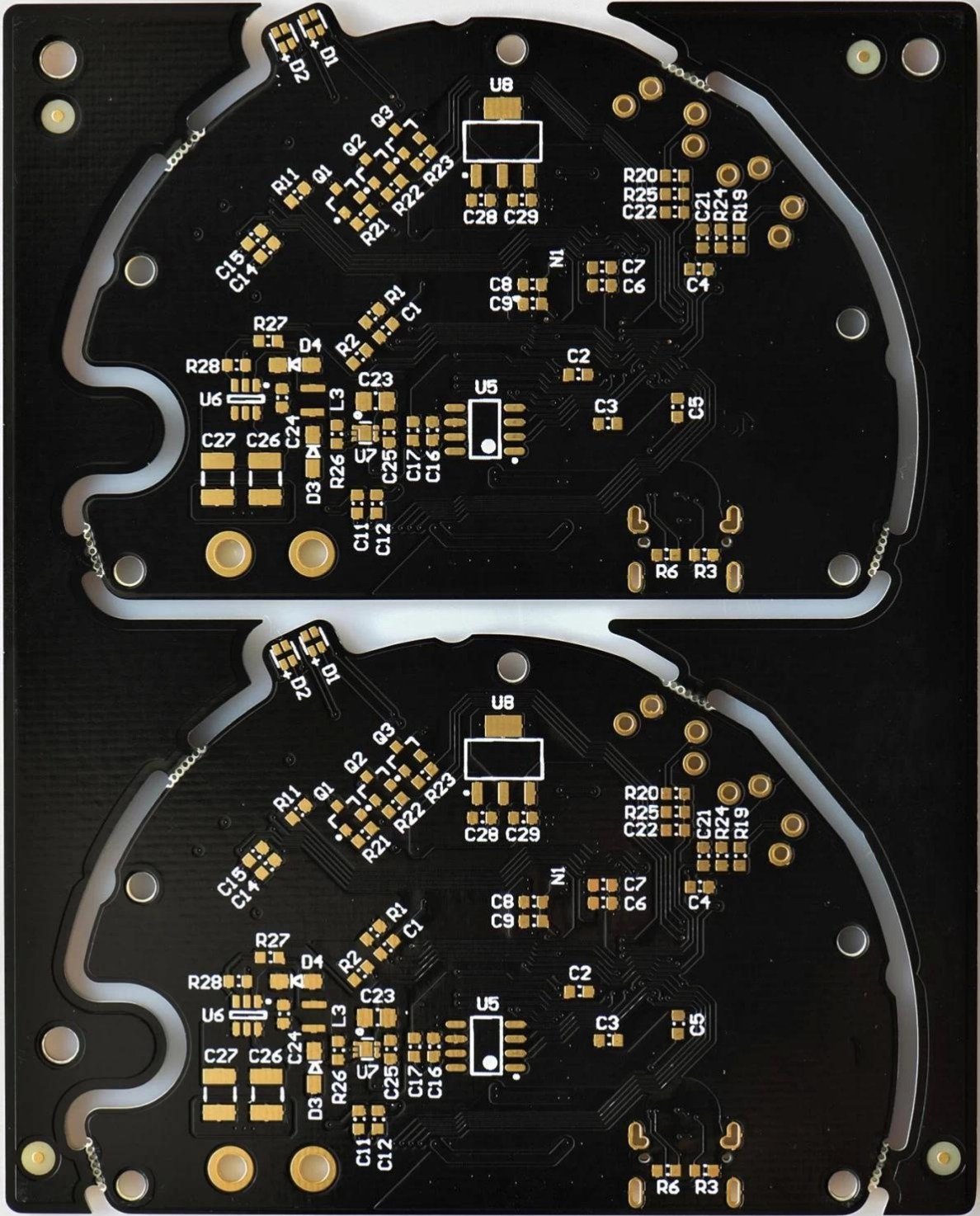
\* .GBL: onderste koperen laag

\* .GBS: Soldeermasker onderaan

\* .GBO: zeefdruk onderaan

\* .GBP: Bodem plakken





## Ons team



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Factory PCB

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Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

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Factory SMT

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# Certificaten

CICC INSPECTION CERTIFICATION



**嘉泰认证**

**QUALITY MANAGEMENT SYSTEM CERTIFICATE**  
Certificate No: 18118Q10347R05

**We hereby certify that**  
**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**  
Credit No: 61691591-000-07-18-7  
Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK  
Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards  
GB/T19001-2016 idt ISO9001:2015

**Scope of certification**  
Sales of printed circuit boards

Initial issuance period: February 27, 2018  
Renewal date: April 22, 2019  
This certificate is valid during: April 22, 2019 – February 26, 2021  
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The indicated information of this certification can be searched on the internet of CICC www.cicc.com.cn






CICC INSPECTION CERTIFICATION



**嘉泰认证**

**质量管理体系认证证书**  
证书号: 18118Q10347R05

**兹证明**  
**诚领供应链（香港）有限公司**  
统一社会信用代码: 61691591-000-07-18-7  
注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室  
经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

**建立的质量管理体系符合**  
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

**认证范围**  
印刷线路板的销售

初次获证日期: 2018年02月27日  
换证日期: 2019年04月22日  
证书有效期: 自2019年04月22日至2021年02月26日  
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次监审	第二次监审	黏贴处
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本证书认证范围不包括未取得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cnca.gov.cn及CICC网站www.cicc.com.cn查询










## ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

## Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**O-LEADING SUPPLY CHAIN (HK) CO LTD**

E490354

ROOM 1205, 12/F  
TAI SANG BANK BLDG  
130-132 DES VOEUS ROAD  
CENTRAL, HONG KONG

Type	Cond Width			SS/ DS/ DSO	Max	Max		Meets UL796	C T	
	Min	Cond	Area		Solder	Oper	Flame			
	Min	Edge								Thk
mm(in)	mm(in)	mic(mil)	mm(in)	C	sec	C	DSR	I		
<b>Multilayer (mass laminate) printed wiring boards.</b>										
<b>O-LEADING-401</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-
<b>O-LEADING-407</b>	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All
<b>Multilayer printed wiring boards.</b>										
<b>O-LEADING-408</b>	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All
<b>Single layer printed wiring boards.</b>										
<b>O-LEADING-002</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All
<b>O-LEADING-003</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲
<b>O-LEADING-033</b>	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All
<b>O-LEADING-205</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All
<b>O-LEADING-206</b>	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All
<b>O-LEADING-D01</b>	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All
<b>O-LEADING-S01</b>	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All

## WIRING, PRINTED - COMPONENT | UL Product iQ

<b>O-LEADING-S02</b>	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲
<b>O-LEADING-S03</b>	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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# Verpakking & Levering

## Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

## Proces capaciteit

### PCB-productiemogelijkheden

Aantal lagen: 1 laag-32 lagen

Afgewerkte koperdikte □ 1 / 3oz-12oz

Min Lijnbreedte / afstand intern □ 3.0mil / 3.0mil

Min Lijnbreedte / afstand extern: 4,0mil / 4,0mil

Max. Beeldverhouding: 10: 1

Plaatdikte □ 0,2 mm - 5,0 mm

Max. Paneelgrootte (inches): 635 \* 1500 mm

Minimale boorgatgrootte: 4mil

Plated Hole Tolerance: +/- 3mil

Blind / Buried Vias (All-typen): JA

Via vulling (geleidend, niet-geleidend): JA

Basismateriaal: FR-4, FR-4hoge Tg. Halogeenvrij materiaal, Rogers, aluminium basis,polyimide,  
Zwaar koper

Oppervlakteafwerkingen: HASL, OSP, ENIG, HAL-LF, Immersion silver,Immersietin, gouden vingers, koolstofinkt

## **SMT-productiemogelijkheden**

PCB-materiaal: FR-4, CEM-1, CEM-3, op aluminium gebaseerde plaat

Maximale printgrootte: 510x460 mm

Min. Printgrootte □ 50x50mm

PCB-dikte □ 0,5 mm - 4,5 mm

Plaatdikte □ 0,5-4 mm

Min. Componentgrootte: 0201

Standaard chipformaat component: 0603 en groter

Component max hoogte □ 15 mm

Min loodsteek: 0,3 mm

Min BGA-balafstand: 0,4 mm

Plaatsingsnauwkeurigheid: +/- 0,03 mm